

AMENDMENTS TO THE CLAIMS

1-20 (Canceled)

21. (Currently amended) The process of making a photoimaged dielectric having a glass transition temperature of at least about 140° C, comprising the steps of

- a) preparing a resin mixture of a polyfunctional epoxy resin comprising triglycidyl ether of tris (hydroxy phenyl) and the condensation product of the bisphenol and epihalohydrin comprising a diglycidyl ether of a bisphenol A
- b) incorporating into the mixture up to 10 PHR of a third epoxy resin capable of improving the flex fatigue life of the dielectric without lowering the glass transition temperature of the dielectric below about 140°C,
- c) incorporating an effective amount of a curing agent comprising a cationic photoinitiator into the mixture,
- d) exposing at least a portion of the mixture to a source of actinic radiation, and
- e) further processing the resin mixture to crosslink the exposed portion of the resin mixture.

22. (Canceled)

23. (Currently amended) The process according to claim 21 wherein the ~~photocationic initiator~~ cationic photoinitiator is a sulfonium compound, and is used in the mixture in an amount of between about 0.5 and about 15 PHR.

24. (Canceled)

25. (Currently amended) The process according to claim 24 21 wherein the third epoxy resin is selected from the group consisting of an epoxidized phenolformaldehyde novolac having a weight per epoxide between about 172 and about 179 and a diglycidyl ether of bisphenol A having a weight per epoxide between about 600 and about 950.

26. (Currently amended) The process according to claim 21 wherein the at least a portion of the resin mixture is exposed to actinic radiation through a pattern.

27. (Previously presented) The process according to claim 26 wherein the resin mixture is further processed in step e) by 1) subjecting the mixture to heat to at least partially cure the exposed portion of the material, 2) removing unexposed material, 3) exposing the partially cured mixture to actinic radiation a second time, and 4) heating to fully cure the mixture to form a polymer.

28. (Currently amended) The process of using a photoimagable polymer capable of forming a film having a glass transition temperature of at least about 140° C, comprising:

- a) preparing a resin mixture of a polyfunctional epoxy resin having more than two epoxy groups and comprising the triglycidyl ether of tris (hydroxy phenyl) and the condensation product of diglycidyl ether of a bisphenol A and an epichlorohydrin, wherein the polyfunctional epoxy comprises between about 30 parts and about 70 parts by weight per 100 parts of the resin mixture, and the condensation product comprises between about 70 parts and about 30 parts by weight per 100 parts of the resin mixture[[.]],
- b) incorporating a cationic photoinitiator into the mixture effective to at least partially cure the mixture upon exposure to actinic radiation,
- c) applying the mixture to an electronic substrate to form a layer thereupon, and
- d) exposing the at least a portion of the layer to a source of actinic radiation to at least partially cure the polymer.

29. (Canceled)

30. (Original) The process according to claim 28 wherein the cationic photoinitiator is selected from the group consisting of a sulfonium compound, an iodonium compound and a ferrocenium-type compound.

31. (Canceled)

32. (Previously presented) The process of making a photoimaged dielectric having a flex fatigue life of at least about 10,000 cycles at about a 3% strain, a Tg of at least about 140° C, and a coefficient of thermal expansion below the glass transition temperature between about 60 and about 80 ppm/° C, comprising the steps of

- a) based on 100 parts by weight of a resin mixture, preparing a mixture of between about 30 parts and about 70 parts of a polyfunctional epoxy resin comprising the triglycidyl ether of tris (hydroxy phenyl) and between about 70 parts and about 30 of a diglycidyl ether of bisphenol A and optionally including the addition to the resin mixture of up to 10 parts of a third epoxy resin capable of improving the flex fatigue life of the polymer without lowering the glass transition temperature below about 140° C wherein the third epoxy resin is selected from the group consisting of an epoxidized phenolformaldehyde novolac having a weight per epoxide between about 172 and about 179 and a

diglycidyl ether of bisphenol A having a weight per epoxide between about 600 and about 950;

- b) incorporating an effective amount of a cationic photoinitiator as a curing agent, comprising a triphenyl sulfonium compound, into the mixture, and
- c) processing the resin mixture including the steps of 1) exposing at least a portion of the layer to a source of actinic radiation, 2) subjecting the exposed portion to heat to at least partially cure the exposed material, 3) removing unexposed material, 4) exposing the partially cured mixture to actinic radiation a second time, and 5) heating to fully cure the partially cured mixture to form the dielectric.

33. (New) The process of using a photoimable polymer capable of forming a film having a glass transition temperature of at least about 140° C, comprising:

- a) preparing a resin mixture of a polyfunctional epoxy resin having more than two epoxy and the condensation product of diglycidyl ether of a bisphenol A and an epichlorohydrin, wherein the polyfunctional epoxy comprises between about 30 parts and about 70 parts by weight per 100 parts of the resin mixture, and the condensation product comprises between about 70 parts and about 30 parts by weight per 100 parts of the resin mixture,

- b) incorporating into the mixture up to 10 PHR of a third epoxy resin capable of improving the flex fatigue life of the polymer without lowering the glass transition temperature below about 140° C,
- c) incorporating a cationic photoinitiator into the mixture effective to at least partially cure the mixture upon exposure to actinic radiation,
- d) applying the mixture to an electronic substrate to form a layer thereupon, and
- e) exposing the at least a portion of the layer to a source of actinic radiation to at least partially cure the polymer.